

Product information

H-Bond is a simple to use dual cure bonding system consisting of the two components H-Bond and H-Bond Activator **that** have to be mixed before application. It is designed for strong bonding of light cure, self-cure and dual cure composites to etched enamel and dentine and to non-precious and precious metals.

H-Bond can be also used for priming the root canals before cementation of endodontic posts with self- or dual cure composites.

H-Bond has the strong adhesion to etched enamel or dentine proceeds on principles similar to that occurring with glass ionomer cements. Good, long lasting adhesive strength and good biocompatibility are attained by polycarboxylic acids.

H-Bond can be used on slightly moist dentine surfaces (wet bonding technique).

1. INDICATIONS

Dual Cure Bonding System for the Total Etch Technique.

2. SIDE EFFECTS

It is essential, that etched areas are not contaminated by anything. If contamination occurs, re-etch, rinse with water and dry as above. Avoid etching gel contact with oral soft tissues, eyes and skin. If accidental contact occurs, flush immediately with copious amounts of water.

3. CAVITY PREPARATION

Rubber dam is the recommended method of isolation.

Cavity floor of deep excavations should be covered with a thin layer of calcium hydroxide material.

Clean the tooth with flour of pumice and water prior to preparation. Prepare the cavity with minimal tooth reduction. Margins should have a slight (0.5 - 1.0 mm) bevel placed in the enamel to increase the surface area for greater bond strength.

Recommended is the total etch technique. Apply H-Etch onto the enamel and dentine surfaces beginning with the enamel bevels. Leave the etching gel in place for 20 seconds. On primary teeth and teeth high in fluoride, a 60 second etch is recommended. Rinse for 20 seconds with water. Dry it in a water and oil-free airstream, but do not desiccate. A slightly wet dentine surface is important for the function of H-Bond. The etched enamel bevel should have a chalky white appearance.

4. APPLICATION AND CURING

For light cure composites

Apply H-Bond generously with a brush onto the enamel and dentin surfaces for 30 seconds with agitation. The material should build a homogeneous layer. Remove excess material carefully. Dry cautiously with oil free air for about 15 seconds to remove all volatile components and to disperse the adhesive to an even layer. Do not desiccate the dentine.

Cure the H-Bond coating by exposing its entire area to a dental halogen light unit for 20 seconds before application of a second layer of H-Bond.

Notes: Do not rinse off the H-Bond! If not used immediately, place dispensed H-Bond in subdued light to prevent premature polymerization by incident light. The H-Bond will not self-cure.

Apply again the H-Bond generously with a brush onto the adhesive surfaces as described above, before placement of a light cure composite.

For self-cure and dual cure composites

One drop of H-Bond and one drop of H-Bond Activator were combined in a mixing pallet and mixed for 5-10 seconds under subdued light.

Apply the H-Bond mixture generously with a brush onto the enamel and dentine surfaces for 30 seconds with agitation. The material should build a homogeneous layer. Remove excess material carefully. Dry cautiously with oil free air for about 15 seconds to remove all volatile components and to disperse the adhesive to an even layer. Do not desiccate the dentine.

Cure the H-Bond coating by exposing its entire area to a dental halogen light unit for 20 seconds before application of a second layer of H-Bond. Without light cure apply the second layer after drying with oil free air.

Apply again the H-Bond mixture generously with a brush onto the adhesive surfaces as described above before placement of a composite.

It is essential that the primed dentine and enamel surfaces are dry and contaminant free for the application of the composite. The self-cure or dual cure composite can be applied immediately.

Application in Root Canals

Prepare and clean the root canal according to the instructions of the selected post manufacturer. Dry the root canal but do not desiccate.

Etch the root canal with H-Etch for 15 seconds and rinse with water using an endodontic irrigation syringe. Blot the canal dry with soft paper tips, leaving the dentin visibly moist. A slightly wet dentine surface is important for the function of H-Bond.

One drop of H-Bond and one drop of H-Bond Activator were combined in a mixing pallet and mixed for 5-10 seconds under subdued light.

Apply H-Bond generously with a suitable brush on the prepared root canal walls for 30 seconds with agitation. The material should build a homogeneous layer.

Remove excess material carefully e.g. with paper points. Dry cautiously with oil free air to remove all volatile components and to disperse the adhesive to an even layer. Do not desiccate.

Optional cure the H-Bond coating by exposing its entire area to a dental halogen light unit for 20 seconds before application of a second layer of H-Bond.

Apply again the H-Bond generously with a brush onto the adhesive surfaces. Optional light cure.

It is essential that the primed dentine and enamel surfaces are dry and contaminant free for the application of the composite. Proceed immediately with placement of the post.

Post Cementation

Prepare the post according to manufacturer instructions.

Place the post with a flow able dual cure or self-cure composite (e.g. HeyTec Core N) into the root canal. For post stabilization light cure the coronal part of the cemented post for 20 seconds.

5.STORAGE

Do not store above 25 °C (78 °F)! Avoid storage in direct sunlight. Do not use after expiration date.

Keep away from children!

6. PRECAUTIONS

Do not interchange lids of the bottles, because this can lead to a cross-contamination of the liquids.

For dental use, only!

7. PACKAGING AND REFERENCE NUMBER

1 bottle H-Bond 5ml	HE001
1 bottle H-Bond Activator 5ml	HE002

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Manufacturing

P.L. Superior Dental Materials GmbH
22607 Hamburg
Germany

Sales

Heydent GmbH
86916 Kaufering
Germany

Made in Germany!

CE 0482